

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

---

<b>Applicant:</b>	Rickie C. Lake	<b>Examiner:</b>	Thomas J. Mullen
<b>Serial No.:</b>	10/788,505	<b>Art Unit:</b>	2612
<b>Filed:</b>	February 26, 2004	<b>Confirmation:</b>	7451
<b>Title:</b>	Thin Profile Battery Bonding Method, Method of Conductively Interconnecting Electronic Components, Battery Powerable Apparatus, Radio Frequency Communication Device, and Electric Circuit		

---

Mail Stop Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT AFTER ALLOWANCE UNDER 37 CFR § 1.312**

Sir:

Applicant respectfully requests the entry of the following amendments prior to the issuance of the above-referenced patent application.